Lithium Ion Pack Supervisor for 3- and 4-Cell Packs

Features

- Protects and individually monitors three or four Li-Ion series cells for overvoltage, undervoltage
- Monitors pack for overcurrent
- Designed for battery pack integration
- Minimal external components
- ► Drives external FET switches
- Selectable overvoltage (Vov) thresholds
 - Mask-programmable by Texas Instruments
 - Standard version–4.25V
- ► Supply current: 25µAtypical
- Sleep current: 0.7µAtypical
- ► 16-pin 150-mil narrow SOIC

General Description

The bq2058 Lithium Ion Pack Supervisor is designed to control the charge and discharge cell voltages for three or four lithium ion (Li-Ion) series cells, accommodating battery packs containing series/parallel configurations. The low operating current does not overdischarge the cells during periods of storage and does not significantly increase the system discharge load. The bq2058 can be part of a low-cost Li-Ion charge control system within the battery pack.

The bq2058 controls two external FETs to limit the charge and discharge potentials. The bq2058 allows charging when each individual cell voltage is below V_{OV} (overvoltage limit). If the voltage on any cell exceeds V_{OV} for a user<u>configurable</u> delay period (tovD), the <u>CHG</u> pin is driven high, shutting off charge to the battery pack. This safety feature pre-

vents overcharge of any cell within the battery pack. After an overvoltage condition occurs, each cell must fall below V_{CE} (charge enable voltage) for the bq2058 to re-enable charging.

The bq2058 protects batteries from overdischarge. If the voltage on any cell falls below V_{UV} (undervoltage limit) for a user-configurable delay period (t_{UVD}), the DSG output is driven high, shutting off the battery discharge. This safety feature prevents overdischarge of any cell within the battery pack.

The bq2058 also stops discharge on detection of an overcurrent condition, such as a short circuit. If an overcurrent condition occurs for a userconfigurable delay period (t_{OCD}), the DSG output is driven high, disconnecting the load from the pack. DSG remains high until removal of the short circuit or overcurrent condition.

Pin Connections



Pin Names

CHG	Charge control output	DSG	Discharge control output
CTL	Pack disable input	NSEL	3- or 4-cell selection
Vec	Low potential input	UVD	Undervoltage delay input
~ 55 CSI	Current sense low side	OVD	Overvoltage delay input
CSL	input	OCD	Overcurrent delay input
BAT _{4N}	Battery 4 negative input	V _{CC}	High potential input
BAT _{3N}	Battery 3 negative input	CSH	Current sense high-side
BAT _{2N}	Battery 2 negative input		input
BAT _{1N}	Battery 1 negative input	BAT _{1P}	Battery 1 positive input

Pin Descriptions

CHG	Charge control output	DSG	Discharge control output
	This push-pull output controls the charge path to the battery pack. Charging is al- lowed when low.		This push-pull output controls the discharge path to the battery pack. Discharge is allowed when low.
CTL	Pack disable input	NSEL	Number of cells input
	When high, this input allows an external source to disable the pack by making both DSG and CHG inactive. For normal operation, the CTL pin is low.		This input selects the number of series cells in the pack. NSEL should connect to V_{CC} for four cells and to V_{SS} for three cells.
Vee	Low notential input	UVD	Undervoltage delay input
CSL	Overcurrent sense low-side input		This input uses an external capacitor to V_{CC} to set the undervoltage delay timing.
	This input is connected between the low-side	OVD	Overvoltage delay input
	to enable overcurrent sensing in the battery pack's ground path.		This input uses an external capacitor to V_{CC} to set the overvoltage delay timing.
BAT _{4N}	Battery 4 negative input	OCD	Overcurrent delay input
	This input is connected to the negative termi- nal of the cell designated BAT4 in Figure 2.		This input uses an external capacitor to V_{CC} to set the overcurrent delay timing.
BAT _{3N}	Battery 3 negative input	Vcc	High potential input
	This input is connected to the negative terminal of the cell designated BAT3 in Figure 2	CSH	Overcurrent sense high-side input
	of the cell designated BAT5 in Figure 2.		This input is connected between the
BAT _{2N}	Battery 2 negative input		high-side discharge FET (or sense resistor)
	This input is connected to the negative termi- nal of the cell designated BAT2 in Figure 2.		the battery pack's positive supply path.
BAT	Battory 1 pogative input	BAT _{1P}	Battery 1 positive input
DAIN	Dattery i negative input		This input is connected to the positive terminal
	This is not is a superstalled the manualized terms		

This input is connected to the negative termi-nal of the cell designated BAT1 in Figure 2.

This input is connected to $BAT_{1P}\xspace$ in a three-cell configuration.

of the cell designated BAT1 in Figure 2.

Number of Cells	Configuration Pins	Battery Pins
		BAT _{1N} – Positive terminal of first cell
2 11 .	$\begin{array}{l} BAT_{1N} \mbox{ tied to } BAT_{1P} \\ NSEL = V_{SS} \end{array}$	BAT _{2N} – Negative terminal of first cell
3 cells		BAT _{3N} – Negative terminal of second cell
		BAT _{4N} – Negative terminal of third cell
4 cells		BAT _{1P} – Positive terminal of first cell
	NSEL = V_{CC}	BAT _{1N} – Negative terminal of first cell
		BAT _{2N} – Negative terminal of second cell
		BAT _{3N} – Negative terminal of third cell
		BAT _{4N} – Negative terminal of fourth cell
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Table 1. Pin Configuration for 3- and 4-Series Cells



Figure 1. Block Diagram

Functional Description

Figure 1 is a block diagram outlining the major components of the bq2058. Figure 2 shows a 3- or 4-cell pack supervisor circuit. The following sections detail the various functional aspects of the bq2058.

Thresholds

The bq2058 monitors the lithium ion pack for the conditions listed below. Shown with these conditions are the respective thresholds used to determine if that condition exists:

 $Overvoltage\left(V_{OV}\right)$

Undervoltage (VUV)

Overcurrent (VOCH, VOCL)

Charge Enable (V_{CE})

Charge Detect (V_{CD})

The bq2058 samples a cell every 40ms (typical). Every sample is a fully differential measurement of each cell. During this sample period, the bq2058 compares the measurements with these thresholds to determine if any of the these conditions exist: V_{OV} , V_{UV} , and V_{CE} .

Overcurrent and charge detect are conditions that are not sampled, but are continuously monitored.

Initialization

On initial power-up, such as connecting the battery pack for the first time to the bq2058, the <u>bq2058</u> enters the low-power sleep mode, disabling the DSG output. It is **recommended that a top to bottom cell connection be made at pack assembly for proper initialization.** A charging supply must be applied to the bq2058 circuit to enable the pack. See Low-Power Sleep Mode and Charge Detect sections.



Figure 2. 3- or 4-Cell Li-Ion Battery Pack Supervisor

Low-Power Sleep Mode

The bq2058 enters the low-power sleep mode in two different ways:

- 1. On initial power-up
- 2. After the detection of an undervoltage condition– $V_{\rm UV}$

When the bq2058 enters the low-power sleep mode, $\overline{\text{DSG}}$ is driven high and the device consumes 0.7µA (typical). The bq2058 only comes out of low-power sleep mode when a valid charge-detect condition exists.

Charge Detect

The bq2058 continuously monitors for a charge-detect condition. A valid charge-detect condition exists when either of the conditions is true:

 $CSL < BAT_{4N} - 70mV (V_{CD})$

 $CSH > BAT_{1P} + 70mV (V_{CD})$

A valid charge-detect enables the $\overline{\text{DSG}}$ output, allowing charging of the lithium ion cells. This is accomplished by applying the charging supply to the pack.

Undervoltage

Undervoltage (or overdischarge) protection is asserted when any cell voltage drops below the $V_{\rm UV}$ threshold and remains below the $V_{\rm UV}$ threshold for a time exceeding a user-configurable delay (tuvp). The DSG output is driven high disabling the discharge of the pack. The bq2058 then enters the low-power sleep mode.

Overvoltage

Overvoltage (or overcharge) protection is asserted when any cell voltage exceeds the V_{OV} threshold and remains above the V_{OV} threshold for a <u>time</u> exceeding a userconfigurable delay (t_{OVD}). The CHG pin is driven high, disabling charge into the battery pack. Charging is disabled until a valid charge enable exists. See Charge Enable section.

Important note: If any battery pin floats (BAT_{1P}, BAT_{1N-4N}), the bq2058 assumes an overvoltage has occurred.

Because of different manufacturers specifications for overvoltage thresholds, the bq2058 can be available with different V_{OV} options. Table 2 summarizes these different voltage thresholds.

Table 2. Overvoltage Threshold Options

Part No.	Vov Limit
bq2058	4.25V
bq2058C	4.325V
bq2058R	4.35V

The overvoltage threshold limits are programmed by Texas Instruments. The bq2058 is the standard option that is more readily available for sampling and prototyping purposes. Please contact your Texas Instruments Sales Representative for other voltage threshold and tolerance options.

Charge Enable

A valid charge enable indicates that an overvoltage (overcharge) condition no longer exists and that the pack is ready to accept further charge. Once overvoltage protection is asserted, charging will not be enabled until all cell voltages fall below V_{CE} . The V_{CE} threshold is a function of V_{OV} and changes with different V_{OV} limits.

 $V_{CE} = V_{OV} - 150 mV$

Overcurrent

The bq2058 detects an overcurrent (or short circuit) condition only in the discharge direction. Overcurrent protection is asserted when either of the conditions occurs and remains for a time exceeding a user-configurable delay (t_{OCD}):

 $CSL > BAT_{4N} + V_{OCL}$

 $CSH < BAT_{1P} \text{ - } V_{OCH}$

where

$$V_{OCL} = 160 \text{mV}$$
 (low-side detect)

 $V_{OCH} = 160 \text{mV}$ (high-side detect)

When either of these conditions occurs, DSG is driven high, disconnecting the load from the pack. DSG remains high until both of the voltage conditions are false, indicating removal of the short-circuit condition. The user can facilitate clearing these conditions by inserting the battery pack into a charger.

The low-side overcurrent sense can be disabled by connecting CSL to BAT_{4N} . This ensures that CSL is never greater than BAT_{4N} . If low-side detection is disabled, high-side detection must be used with CSH.

The FETs in the charge/discharge path controlled by the CHG and DSG pins affect the overcurrent level. The on-resistance of these FETs need to be taken into account when determining overcurrent levels.

Condition	CHG pin	DSG pin
Normal operation	Low	Low
Overvoltage	High	Low
Undervoltage	Low	High
Overcurrent	Low	High
Floating battery input	High	Indeterminate
CTL = high	High	High

CHG and DSG States

The \overline{CHG} and \overline{DSG} output truth table is shown below.

The polarities of \overrightarrow{CHG} and \overrightarrow{DSG} are mask programmable at Texas Instruments. Push-pull vs. open-drain configuration is also mask-configurable at Texas Instruments. Please contact your Texas Instruments Sales Representative for availability of these variations.

Number of Cells

The user must configure the bq2058 for three- or fourseries cell operation. For a three-cell pack, NSEL should be tied directly to V_{SS} . For a four-cell pack, N_{SEL} should be connected directly to V_{CC} .

Number of Series Cells	NSEL
3-cell	Tied to V _{SS}
4-cell	Tied to V _{CC}

Pack Disable Input–CTL

The CTL pin is used to electrically disconnect the battery from the pack terminals through an <u>externally supplied</u> signal. When CTL is taken high, CHG and DSG are driven high. Any load on the pack terminals will be interpreted as an overcurrent condition by the bq2058 with the overcurrent delay timer held in reset. When the CTL pin is driven low, the overcurrent delay timer is allowed to start. If the programmed delay (t_{OCD}) is too short, the overcurrent recovery circuit, if implemented, will be unable to correct the overcurrent situation prior to the delay time-out. It is recommended that a delay time of greater than 10ms (C_{OCD} $\geq 0.01\mu$ F) be used if the CTL pin function is used.

Important note: If CTL <u>floats</u>, it <u>is internally</u> pulled high making both DSG and CHG inactive, thus disabling the pack. If CTL is not used, it should be tied to V_{SS} .

The polarity of CTL is mask programmable at Texas Instruments. Please contact your Texas Instruments Sales Representative for other polarity options.

Protection Delay Timers

The delay time between the detection of an overcurrent, overvoltage, or undervoltage condition and the deactivation of the CHG and/or $\overline{\text{DSG}}$ outputs is user-configurable by the selection of capacitor values between V_{CC} and OCD, OVD, and UVD pins (respectively). See Table 3 below.

The fault condition must persist through the entire delay period, or the bq2058 may not deactivate either FET control output.

Figure 3 shows a step-by-step event cycle for the bq2058.

Table 3. Protection Delay Timers

Protection	Delay	Canacitor from	Тур	ical	
Feature	Period	V _{CC} to:	Capacitor	Time	Tolerance
Overcurrent	t _{OCD}	OCD	0.010µF	12ms	±40%
Overvoltage	tovD	OVD	0.100µF	950ms	±40%
Undervoltage	t _{UVD}	UVD	0.100µF	950ms	±40%

Notes: 1. The delay time versus capacitance can be approximated by the following equations:

For t_{OVD} , t_{UVD} : $t_{(s)} \approx 9.5 * C_{(\mu f)}$, where $C \ge 0.01 \mu F$

2. Overvoltage and undervoltage conditions are sampled by the bq2058. The delay in Table 2 is in addition to the time required for the bq2058 to detect the violation, which may vary from 0 to 160ms depending on where in the sampling period the violation occurs. Overcurrent is continuously monitored and is subject to a delay of approximately 1.5ms.

For t_{OCD}: $t_{(s)} \approx 1.2 * C_{(\mu f)}$, where $C \ge 0.001 \mu F$



Figure 3. Protector Event Diagram

Event Definition

- 0: The bq2058 is in the low-power sleep mode because one or more of the cell voltages are below V_{UV}.
- 1: A charger is applied to the pack, causing the difference between CSH and BAT_{1P} to become greater than 70mV. This awakens the bq2058, and the discharge pin DSG goes low.
- 2: One or more cells charge to a voltage equal to Vov, initiating the overvoltage delay timer.
- 3: The overvoltage delay time expires, causing \overline{CHG} to be driven high.
- 4: All cell voltages fall below V_{CE} , causing \overline{CHG} to be driven low.
- 5: Stop charging; apply a load.
- 6: An overcurrent condition is detected, initiating the overcurrent delay timer.
- 7: The overcurrent delay time expires, causing $\overline{\text{DSG}}$ to be driven high.
- 8: The overcurrent condition is no longer present; DSG is driven low.
- 9: Pin CTL is driven high; both $\overline{\text{DSG}}$ and $\overline{\text{CHG}}$ are driven high.
- 10: Pin CTL is driven low; both $\overline{\text{DSG}}$ and $\overline{\text{CHG}}$ resume their normal function.
- 11: One or more cells fall below V_{UV}, initiating the overdischarge delay timer.
- 12: Once the overdischarge delay timer expires, if any of the cells is below V_{UV} , the bq2058 drives \overline{DSG} high and enters the low-power sleep mode.

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit	Conditions
V _{CC}	Supply voltage	18	v	Relative to V _{SS}
T _{OPR}	Operating temperature	-30 to +70	°C	
T _{STG}	Storage temperature	-55 to +125	°C	
T _{SOLDER}	Soldering temperature	260	°C	For 10 seconds
I _{IN}	Maximum input current	±100	μΑ	All pins except V _{CC} , V _{SS}

Notes: 1 Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

2. Internal protection diodes are in place on every pin relative to V_{CC} and $V_{SS}.$ See Figure 4.



Figure 4. Internal Protection Diodes

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Conditions/Notes
V _{OH}	Output high voltage	V _{CC} - 0.5	-	-	V	$I_{OH} = 10\mu A, \overline{CHG}, \overline{DSG}$
V _{OL}	Output low voltage	-	-	$V_{SS} + 0.5$	v	$I_{OL} = 10\mu A, \overline{CHG}, \overline{DSG}$
V _{OP}	Operating voltage	4	-	18.0	v	V _{CC} relative to V _{SS}
VIL	Input low voltage	-	-	$V_{SS} + 0.5$	v	Pin CTL
V _{IH}	Input high voltage	V _{SS} + 2.0	-	-	v	Pin CTL
VIL	Input low voltage	-	-	$V_{SS} + 0.5$	v	Pin NSEL
V _{IH}	Input high voltage	V _{CC} - 0.5	-	-	-	Pin NSEL
I _{CCA}	Active current	-	25	40	μΑ	
I _{CCS}	Sleep current	-	0.7	1.5	μΑ	

DC Electrical Characteristics (TA = TOPR)

DC Thresholds (TA = TOPR)

Symbol	Parameter	Value	Unit	Tolerance	Condition
37	Overvoltage threshold	4.25	V	±50mV	See note 1.
VOV	(See Figure 5.)		Table	2	Customer option
V _{CE}	Charge enable threshold	V _{OV} - 150mV	v	±50mV	
V _{UV}	Undervoltage threshold	2.25	v	±100mV	
V _{OCH}	Overcurrent detect high-side	160	mV	±35mV	
V _{OCL}	Overcurrent detect low-side	160	mV	±35mV	
V _{CD}	Charge detect threshold	70	mV	-60mV, +80mV	
t _{OVD}	Overvoltage delay threshold	950	ms	±40%	$C_{OVD} = 0.100 \mu F$, $T_A = 30^{\circ}C$ See note 2.
t _{UVD}	Undervoltage delay threshold	950	ms	±40%	$C_{UVD} = 0.100\mu$ F, $T_A = 30^{\circ}$ C See note 2.
t _{OCD}	Overcurrent delay threshold	12	ms	±40%	$C_{OCD} = 0.01 \mu F, T_A = 30^{\circ}C$

1. Standard device. Contact your Texas Instruments Sales Representative for different thresholds and Notes:

tolerance options.2. Does not include cell sampling delay, which may add up to 160ms of additional delay until the condition is detected.

Impedance

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
R _{CELL}	Input impedance	-	10	-	MΩ	Pins BAT _{1P,} BAT _{1N-4N,} CSH, CSL



Figure 5. bq2058 4.25V Overvoltage Threshold vs. Free-Air Temperature

Change No.	Page No.	Description	Nature of Change		
1	1, 2, 5	PACK+, PACK-	Pins renamed to CSH and CSL respectively		
1	1	Pin description	Added CSH/CSL description		
1	3	Block diagram	Update Block diagram		
1	4	Figure 2	Update typical application circuit		
1	4	Configuration description	Correction to description		
1, 2	5	Overcurrent limits	$ \begin{array}{l} Was: \ V_{OCH} = 150mV \pm \ 25mV \\ V_{OCL} = 85mV \pm 25mV \\ Is: \ V_{OCH} = 160mV \pm \ 25mV \\ V_{OCL} = 100mV \pm \ 25mV \end{array} $		
1	7	Figure 3	Update Event diagram		
1, 2	9	DC threshold	$ \begin{array}{l} \mbox{Was: } V_{OCH} = 150mV \pm 25mV \\ V_{OCL} = 100mV \pm 80mV \\ V_{CD} = 70mV - 60, +50mV \\ \mbox{Is: } V_{OCH} = 160mV \pm 25mV \\ V_{OCL} = 100mV \pm 25mV \\ V_{CD} = 70mV - 60, +80mV \end{array} $		
3	1, 3, 5	High-side overcurrent monitored	Was: Between V _{CC} and CSH, Is: Between BAT _{1P} and CSH		
3	4	Overvoltage threshold options	Added bq2058R		
3	3, 5	Overcurrent limit	Was: $V_{OCL} = 100 \text{mV}$, Is: $V_{OCL} = 150 \text{mV}$		
4	4	Figure 2	Corrected schematic		
4	6, 8	Protection Delay Times	Was: $t_{OCD} = 10ms \pm 30\%$ $t_{OVD} = 800ms \pm 30\%$ $t_{UVD} = 800ms \pm 40\%$ Is: $t_{OCD} = 12ms \pm 40\%$ $t_{OVD} = 950ms \pm 40\%$ $t_{UVD} = 950ms \pm 40\%$		
4	10	Overcurrent limits	$ \begin{array}{l} \mbox{Was: } V_{OCH} = 160 mV \pm 25 mV \\ V_{OCL} = 150 mV \pm 25 mV \\ \mbox{Is: } V_{OCH} = 160 mV \pm 35 mV \\ V_{OCL} = 160 mV \pm 35 mV \end{array} $		
5	5, 9	Overvoltage threshold Charge enable threshold Undervoltage threshold	Added bq2058W		
6	9	DC electrical characteristics	Was: Minimum $V_{OP} = 0V$, Is: Minimum $V_{OP} = 4V$		
7	5, 9	Overvoltage threshold	Added bq2058C and bq2058G		
8	4	Reference circuit amended	Moved D1 to new location		
9	5, 9	Overvoltage thresholds	Removed bq2058D, bq2058F, bq2058G, bq2058J, bq2058K, bq2058M, and bq2058W		

Data Sheet Revision History

Notes: Change 1 = Feb. 1997 B changes from Jan. 1997 A. Change 2 = April 1997 C changes from Feb. 1997 B. Change 3 = June 1997 D changes from April 1997 C. Change 4 = July 1997 E changes from June 1997 D. Change 5 = Feb. 1998 F changes from July 1997 E. Change 6 = May 1998 G changes from Feb. 1998 F. Change 7 = June 1998 H changes from May 1998 G. Change 8 = Jan. 1999 I changes from June 1998 H. Change 9 = July 2000 SLUS070A changes from Jan. 1999 I.

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Ordering Information



Package Devices						
TA	V _{OV} Threshold	16-pin Narrow SOIC (SN)				
-30°C to +70°C	4.25V	bq2058SN				
	4.325	bq2058CSN				
	4.35V	bq2058RSN				

Notes: bq2058SN is Standard Device.

Contact your Texas Instruments Sales Representative for availability of other thresholds and tolerances.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
BQ2058CSN-C5	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
BQ2058CSN-C5TR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
BQ2058CSN-C5TRG4	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
BQ2058DSN-C5	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
BQ2058RSN-C5	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
BQ2058RSN-C5TR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
BQ2058SN-C5	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
BQ2058SN-C5TR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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